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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

DUBIN et al

Serial No.:

**10 99**/046,218

Filed:

January 16, 2002

For:

Apparatus And Method For Electroless Spray

Deposition

Art Unit:

1762

Examiner:

M. Barr

## <u>AMENDMENT</u>

Mail Stop Amendment Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-1450

May 19, 2003

Sir:

This is in response to the Office Action mailed March 31, 2003, in connection with the above-identified application.

IN THE CLAIMS:

Please amend the claims to read as follows.

1. (Amended) An apparatus for electroless spray deposition of a metal layer on a substrate, comprising:

a processing chamber to hold at least one substrate on which the metal layer is to be deposited, the processing chamber including at least one section movable between an open position to allow the at least one substrate to be introduced into and removed from the processing chamber and a closed position to seal the processing chamber to allow for pressurization of the processing chamber;

an inlet to provide pressurizing gas to the processing chamber;

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